

Title (en)

AFTER-TREATMENT PROCESS FOR INCREASING THE HOT STRENGTH OF A SHAPED PART PRODUCED FROM PARTICULATE MATERIAL AND BINDER, 3D PRINTING ARRANGEMENT AND SHAPED PART

Title (de)

NACHBEHANDLUNGSVERFAHREN ZUR ERHÖHUNG DER HEIßFESTIGKEIT EINES AUS PARTIKELMATERIAL UND BINDEMittel GEFERTIGTEN FORMTEILS, 3D-DRUCK-ANORDNUNG UND FORMTEIL

Title (fr)

PROCÉDÉ DE RETRAITEMENT DESTINÉ À L'AUGMENTATION DE LA RÉSISTANCE À CHAUD D'UNE PIÈCE MOULÉE RÉALISÉE AVEC UN MATÉRIAU PULVÉRULENT ET UN LIANT, UN ENSEMBLE D'IMPRESSION 3D ET UNE PIÈCE MOULÉE

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Application

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Abstract (en)

[origin: WO2018215113A1] The invention provides an after-treatment process for increasing the hot strength of a shaped part (100) produced from particulate material and binder in which the shaped part (100) is a shaped part produced by 3D printing (S72) and, after its production, is heated by using a heating device (40) (S30) and the heated shaped part (100) is exposed to an atmosphere created by feeding in water and enriched with gaseous water (S50).

IPC 8 full level

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Citation (search report)

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